PALOMAR TECHNOLOGIES

Data Sheet

8000i WIRE BONDER / BALL (STUD) BUMPER

High-Reliability I Precision I Repeatability

The 8000i Wire Bonder is a fully automatic, thermosonic, high-speed Au/Pt bumper, ball and wire bonder. The 8000i Wire Bonder supports complex, high-mix automated production for wire bonding, ball/stud bumping and complex IC attach.

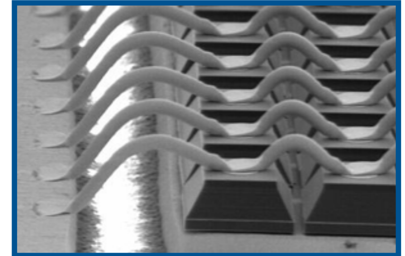
The 8000i comes equipped with **Intelligent Interactive Graphical Interface™** (**i_2Gi™**), a revolutionary software capability for modern wire bonding.

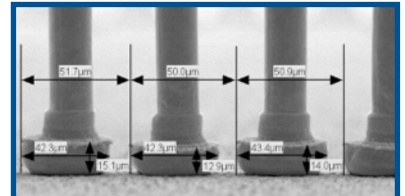
8000i Wire Bonder Configurations for Automated Production

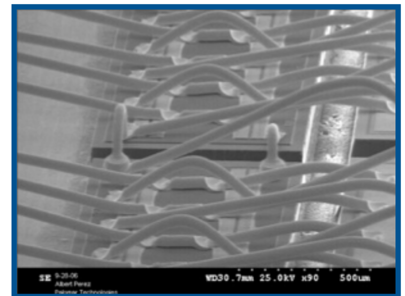
Automated production line with customizable magazine handlers and hotrail conveyors. Ideal for high-mix, complex automated production.

Ergonomic kit that supports both traditional keyboard and track-ball or a large glove-touch compatible touch screen (optional). Ideal for complex programming and intuitive control of part builds.

Standard for reduced footprint and automated production scalability. Ideal for complex hybrid device packaging with flexibility to meet changing production needs.







CYCLE TIME
0.125 sec/wire; 0.077 sec/bump

PLACEMENT ACCURACY
+/- 2.5 micron, 3 sigma

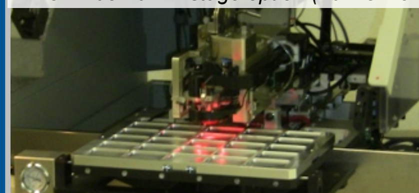
LARGE WORK AREA
304.8 x 152.4 mm (12 x 6 inch)

MULTIPLE FEATURES
- Tailless bump mode
- Stand-off stitch wires
- Cognex video
- One-step planar gold bumps
- Tall multi-level bonding (>12.7mm, >0.50 inch)
- Chain bonding
- TAB bonding
- Adaptive bond deformation
- True perpendicular bonding to consistently produce high-quality bonds at varying surface heights over a 20mm range (0.78 inch)

VERSATILITY
- Wire bonder and ball bumper
- Deep access with capillary of 11.10-19.05mm (0.437-0.75 inch) capillaries available
- In-line and magazine handlers
- SMEMA compatible

BOND DATA MINER™
comprehensive and centralized data management and analysis system
- Aggregates run data into timestamped data sets
- Process analysis tool
- Machine and process trends monitoring for increased yields and predictive maintenance

245 x 203.20mm stage option (10 x 8 inch)



COMMON APPLICATIONS*
- Large Complex Hybrids
- System in Packages (SiPs)
- Multi-Chip Modules (MCMs)
- Automotive Assemblies
- LEDs with Running Stitch
- Disk Drive Assemblies
- Flex Circuits
- HB/HP LED Arrays
- Optoelectronic Packaging
- Chip on Board (COB)
- Solar Concentrator Packaging
- Specialty Lead Frames
- Fine Pitch Devices

*partial list